

U.S. Patent Documents

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Initial	No.	Patent No.	Date	Patentee	Class	class	Date
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Foreign Patent or Published Foreign Patent Application

Examiner		Document	Publication	Country or		Sub-	Tran	slation
Initial	No.	No.	Date	Patent Office	Class	class	Yes	No
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Examiner 6	De	16.	Date Considered 3/3/06

Form 1449 (Modified)

Information Disclosure
Statement By Applicant

(Use Several Sheets if Necessary)

Atty Docket No. Application No.:

NSC1P131X1

Applicant:

NGUYEN et al.

Filing Date

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2/21/2002

2814

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Foreign Patent or Published Foreign Patent Application

Examiner		Document	Publication	Country or		Sub-	Trans	slation
Initial	No.	No.	Date	Patent Office	Class	class	Yes	No
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Form 1449 (Medifier)

Information Disclosure Statement By Applicant

(Use Several Sheets if Necessary)

Atty Docket No.

NSC1P131X1/P04314P01

Application No.: 10/080,913

Applicant:

Nguyen et al.

Filing Date

Group

February 21, 2002 2814

**U.S. Patent Documents** 

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NSC1P131X1/P04314P01 10/080,913

Applicant:

Nguyen et al.

Filing Date Group

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U.S. Patent Documents

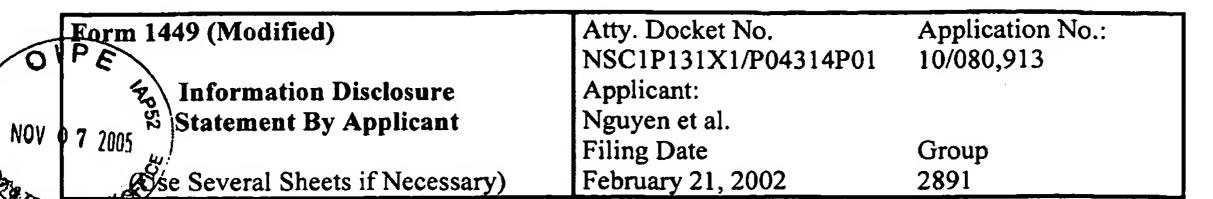
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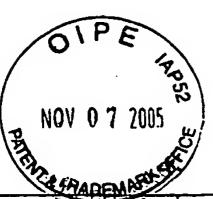


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Examiner		Document	Publication	Country or		Sub-	Trans	slation
Initial	No.	No.	Date	Patent Office	Class	class	Yes	No
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Form 1449 (Madified)

Information Disclosure
Statement By Applicant

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Atty Docket No. Application No.:

NSC1P131X1
10/080,913

Applicant:

Nguyen et al.

Filing Date
02/21/02
2823

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Foreign Patent or Published Foreign Patent Application

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Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
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Examiner	2	Date Considered 3)3/06